

## **DATE 29 JAN 2013**

## NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- Y14.5M, 1994.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION b APPLIES TO THE PLATED TERMINAL AND IS MEASURED ABETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.

  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	-	0.80	
A1	0.00	0.05	
А3	0.20 REF		
b	0.15	0.25	
D	7.00 BSC		
D2	5.10	5.30	
E	7.00 BSC		
E2	5.10	5.30	
е	0.40 BSC		
L	0.30	0.50	
L1	0.00	0.15	

## **GENERIC MARKING DIAGRAM\***



= Assembly Location

WL = Wafer Lot YY = Year

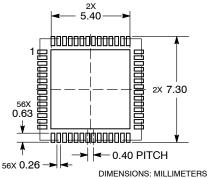
WW = Work Week

G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

## RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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